

05-06-2004



Form PTO-1595 (Rev. 03/01) OMB No. 0651-0027 (exp. 5/31/2002)

U.S. DEPARTMENT OF COMMERCE U.S. Patent and Trademark Office

102738973

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof

1. Name of conveying party(ies): Tsukasa Sugawara (04/21/2004), Akira Fujii (04/21/2004), and Hajime Shimada (04/22/2004) 4-30-04 Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies) Name: Hitachi High-Technologies Corporation Internal Address: Street Address: 24-14, Nishishimbashi 1-chome Minato-ku Tokyo JAPAN City: State: Zip: Additional name(s) & address(es) attached: Yes No

22386 U.S. PTO 10/834856



3. Nature of Conveyance: X Assignment Merger Security Agreement Change of Name Other Execution Date: April 22, 204

4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the new application is: April 30, 2004 A. Patent Application No.(s): This application 10834856 B. Patent No.(s): Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed: Name: Mark J. Thronson DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP Internal Address: Atty. Dkt.: N9460.0029/P029 Street Address: 2101 L Street NW City: Washington State: DC Zip: 20037-1526

6. Total number of applications and patents involved: 1 7. Total fee (37 CFR 3.41) \$ 40.00 Enclosed X Authorized to be charged to deposit account X Authorized to be charged to credit card (Form 2038 enclosed) 8. Deposit account number: 04-1073 (Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Mark J. Thronson (33,082) Name of Person Signing Signature April 30, 2004 Date

Total number of pages including cover sheet, attachments, and documents: 2

05/03/2004 AADDF01 00000027 10834856 40.00 OP 02 FC:8021

ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI HIGH-TECHNOLOGIES CORPORATION, a corporation organized under the laws of Japan, located at 24-14 Nishi Shinbashi 1-chome, Minato-ku, Tokyo 105-8717, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI HIGH-TECHNOLOGIES CORPORATION, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to
CIRCUIT BOARD MODULE, CIRCUIT BOARD CHASSIS AND ELECTROMAGNETIC SHIELDING PLATE THEREFOR

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI HIGH-TECHNOLOGIES CORPORATION, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI HIGH-TECHNOLOGIES CORPORATION.

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Tsukasa SUGAWARA</u> <i>Tsukasa Sugawara</i>	<u>4/21/2004</u>
2) <u>Akira FUJII</u> <i>Akira Fujii</i>	<u>4/21/2004</u>
3) <u>Hajime SHIMADA</u> <i>Hajime Shimada</i>	<u>4/22/2004</u>
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____